

U.S. Patent Application Serial No. 10/612,990
Response filed September 5, 2006
Reply to OA dated June 5, 2006

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended): A multilayer circuit board, comprising:

a plurality of cable layers, each of which includes electric conductive sections;

a plurality of first insulating layers, each of which encloses said electric conductive sections in each cable layer and fills spaces between said electric conductive sections, each of said electric conductive sections of each of said cable layers including a cable pattern and a land pad;

post vias electrically connecting said electric conductive sections in one cable layer to those in another cable layer,

wherein height of said electric conductive sections in each cable layer are ~~regulated by abrading to be~~ equal to that of said first insulating layer enclosing ~~those~~ said electric conductive sections; and

a second insulating layer, which is formed to enclosed said post vias,

wherein height of said post vias ~~are regulated by abrading to be~~ equal to that of said second insulating layer, and

each said first insulating layer and each said second insulating layer are of a non-porous body material.

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Claim 2 (Canceled)

Claim 3 (Canceled)

Claim 4 (Canceled)

Claim 5 (Canceled)

Claim 6 (Canceled)

Claim 7 (Canceled)

Claim 8 (Canceled)

Claim 9 (Canceled)

Claim 10 (Canceled)